

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: Tsutomu SATO et al.

GAU:

SERIAL NO: New Application

EXAMINER:

FILED: Herewith

FOR: SEMICONDUCTOR DEVICE FORMED IN SEMICONDUCTOR LAYER ARRANGED ON  
SUBSTRATE WITH ONE OF INSULATING FILM AND CAVITY INTERPOSED BETWEEN THE  
SUBSTRATE AND THE SEMICONDUCTOR LAYER

**REQUEST FOR PRIORITY**

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

☒ Full benefit of the filing date of U.S. Application Serial Number 10/091,448, filed March 7, 2002, is claimed pursuant to the provisions of **35 U.S.C. §120**.

☐ Full benefit of the filing date(s) of U.S. Provisional Application(s) is claimed pursuant to the provisions of **35 U.S.C. §119(e)**: Application No. Date Filed

☒ Applicants claim any right to priority from any earlier filed applications to which they may be entitled pursuant to the provisions of **35 U.S.C. §119**, as noted below.

In the matter of the above-identified application for patent, notice is hereby given that the applicants claim as priority:

**COUNTRY**

Japan

**APPLICATION NUMBER**

2001-398184

**MONTH/DAY/YEAR**

December 27, 2001

Certified copy of the corresponding Convention Application(s)

☐ are submitted herewith

☐ will be submitted prior to payment of the Final Fee

☒ was filed in prior application Serial No. 10/091,448 filed March 7, 2002

☐ were submitted to the International Bureau in PCT Application Number  
Receipt of the certified copies by the International Bureau in a timely manner under PCT Rule 17.1(a) has been acknowledged as evidenced by the attached PCT/IB/304.

☐ (A) Application Serial No.(s) were filed in prior application Serial No. filed ; and

☐ (B) Application Serial No.(s)

☐ are submitted herewith

☐ will be submitted prior to payment of the Final Fee

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,  
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22850

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